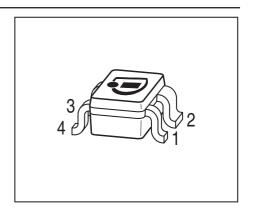


Low Noise Silicon Bipolar RF Transistor

- For highest gain and low noise amplifier
- Outstanding G_{ms} = 21.5 dB at 1.8 GHz
 Minimum noise figure NF_{min} = 0.9 dB at 1.8 GHz
- Pb-free (RoHS compliant) and halogen-free package with visible leads
- Qualification report according to AEC-Q101 available







ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration				Package		
BFP540	ATs	1=B	2=E	3=C	4=E	-	-	SOT343

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}		V
<i>T</i> _A = 25 °C		4.5	
<i>T</i> _A = -55 °C		4	
Collector-emitter voltage	V_{CES}	14	
Collector-base voltage	V_{CBO}	14	
Emitter-base voltage	V _{EBO}	1	
Collector current	I _C	80	mA
Base current	I _B	8	
Total power dissipation ¹⁾	P _{tot}	250	mW
<i>T</i> _S ≤ 77°C			
Junction temperature	T_{J}	150	°C
Ambient temperature	T_{A}	-65 150	
Storage temperature	T_{Stg}	-65 150	

 $^{^{1}}T_{\mathrm{S}}$ is measured on the emitter lead at the soldering point to the pcb



Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	290	K/W

Electrical Characteristics at $T_{\rm A}$ = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	•		•		•
Collector-emitter breakdown voltage	V _{(BR)CEO}	4.5	5	-	V
$I_{\rm C}$ = 1 mA, $I_{\rm B}$ = 0	, ,				
Collector-emitter cutoff current	I _{CES}	-	-	10	μΑ
$V_{CE} = 14 \text{ V}, V_{BE} = 0$					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{CB} = 5 \text{ V}, I_{E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	10	μΑ
$V_{\rm EB} = 0.5 \rm V, \it I_{\rm C} = 0$					
DC current gain	h _{FE}	50	110	185	-
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 3.5 V, pulse measured					

 $^{^{1}}$ For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Symbol	Values			Unit
	min.	typ.	max.	
g)	1	T	·	·
f _T	21	30	-	GHz
C _{cb}	-	0.14	0.24	pF
C _{ce}	-	0.33	-	
C _{eb}	-	0.65	-	
NF _{min}				dB
	-	0.9	1.4	
	-	1.3	-	
G _{ms}	-	21.5	-	dB
G _{ma}	-	16	_	dB
$ S_{21e} ^2$				dB
	16	18.5	-	
	-	14.5	-	
IP3	-	24.5	-	dBm
P _{-1dB}	-	11	-	
			I	1
	Symbol g) fT C _{cb} C _{eb} NF _{min} G _{ms} S _{21e} ²	Symbol min.	min. typ. g) fT 21 30 C _{cb} - 0.14 C _{ce} - 0.33 NF _{min} - 0.9 - 1.3 G _{ms} - 21.5 S _{21e} ² 16 18.5 - 14.5 P3 - 24.5	Symbol min. typ. max. g) T 21 30 - C_{cb} - 0.14 0.24 C_{ce} - 0.33 - NF_{min} - 0.9 1.4 - 1.3 - G_{ms} - 21.5 - G_{ma} - 16 - $ S_{21e} ^2$ - 18.5 - $IP3$ - 24.5 -

 $^{^{1}}G_{\text{ma}} = |S_{21e} / S_{12e}| \text{ (k-(k^2-1)^{1/2}), } G_{\text{ms}} = |S_{21e} / S_{12e}|$

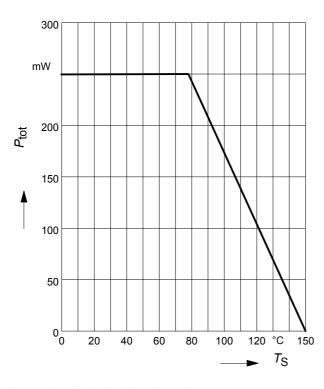
 $^{^2\}mbox{IP3}$ value depends on termination of all intermodulation frequency components.

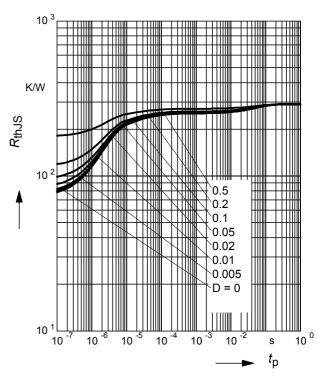
Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz



Total power dissipation $P_{tot} = f(T_S)$

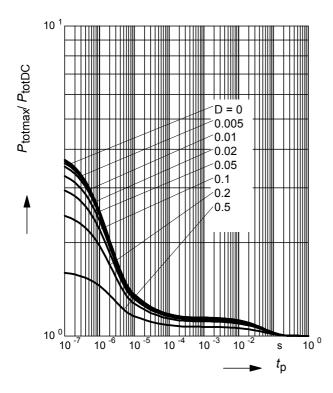
Permissible Pulse Load $R_{thJS} = f(t_p)$



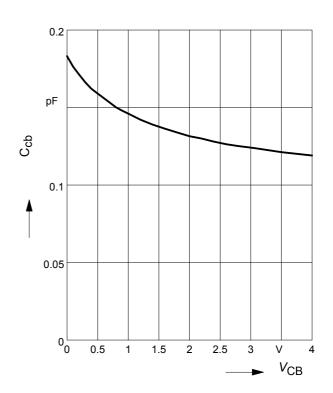


Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$



Collector-base capacitance C_{cb} = $f(V_{CB})$ f = 1MHz

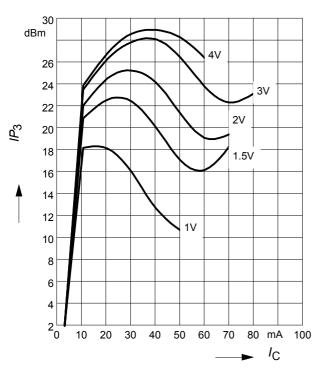




Third order Intercept Point $IP_3 = f(I_C)$

(Output, $Z_S = Z_L = 50\Omega$)

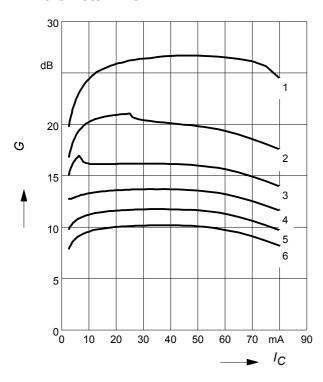
 V_{CE} = parameter, f = 1.8GHz



Power gain G_{ma} , $G_{ms} = f(I_C)$

 $V_{CE} = 2V$

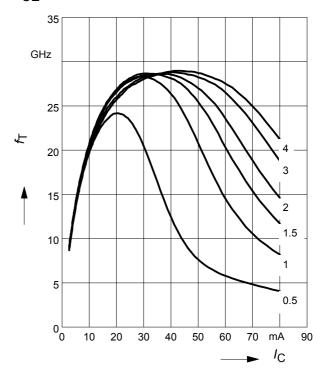
f = Parameter in GHz



Transition frequency $f_T = f(I_C)$

f = 1 GHz

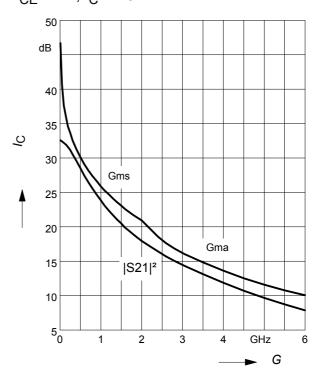
 V_{CE} = Parameter in V



Power Gain G_{ma} , $G_{ms} = f(f)$,

$$|S_{21}|^2 = f(f)$$

$$V_{CE} = 2V, I_{C} = 20mA$$

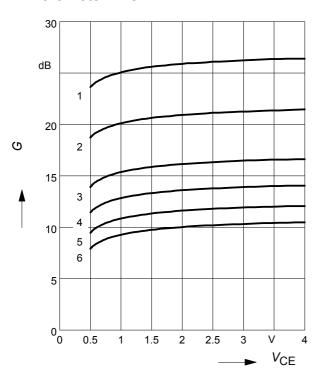




Power gain G_{ma} , $G_{\text{ms}} = f(V_{\text{CE}})$

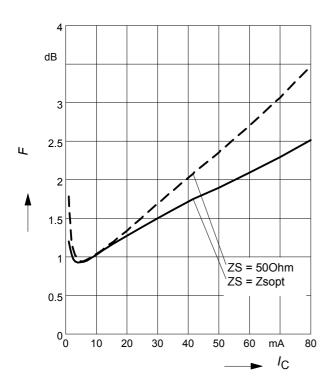
 $I_{\rm C}$ = 20mA

f = Parameter in GHz



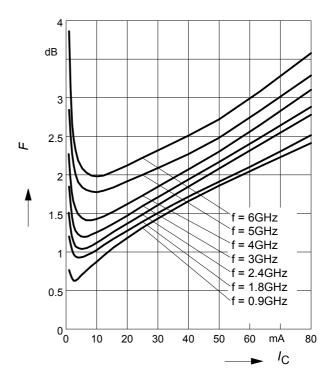
Noise figure $F = f(I_{\mathbb{C}})$

$$V_{CE} = 2V, f = 1.8GHz$$



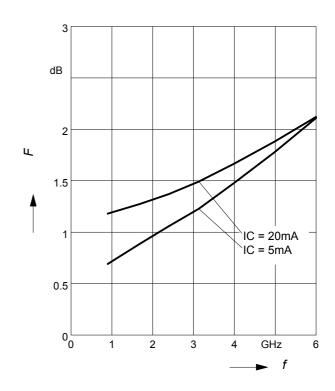
Noise figure $F = f(I_C)$

$$V_{CE}$$
 = 2V, Z_{S} = Z_{Sopt}



Noise figure F = f(f)

$$V_{CE}$$
 = 2V, Z_{S} = Z_{Sopt}

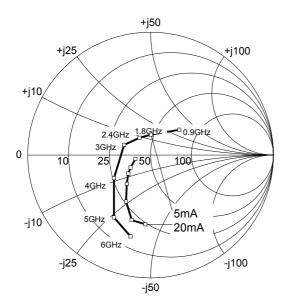




Source impedance for min.

noise figure vs. frequency

 $V_{\rm CE}$ = 2V, $I_{\rm C}$ = 5mA / 20mA





SPICE GP Model

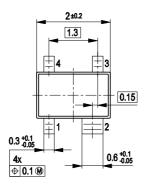
For the SPICE Gummel Poon (GP) model as well as for the S-parameters (including noise parameters) please refer to our internet website www.infineon.com/rf.models.

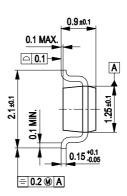
Please consult our website and download the latest versions before actually starting your design. You find the BFP540 SPICE GP model in the internet in MWO- and ADS-format, which you can import into these circuit simulation tools very quickly and conveniently. The model already contains the package parasitics and is ready to use for DC and high frequency simulations. The terminals of the model circuit correspond to the pin configuration of the device. The model parameters have been extracted and verified up to 10 GHz using typical devices. The BFP540 SPICE GP model reflects the typical DC- and RF-performance within the limitations which are given by the SPICE GP model itself. Besides the DC characteristics all S-parameters in magnitude and phase, as well as noise figure (including optimum source impedance, equivalent noise resistance and flicker noise) and intermodulation have been extracted.



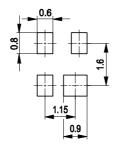
Package Outline



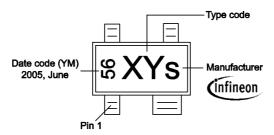




Foot Print

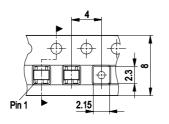


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel







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